

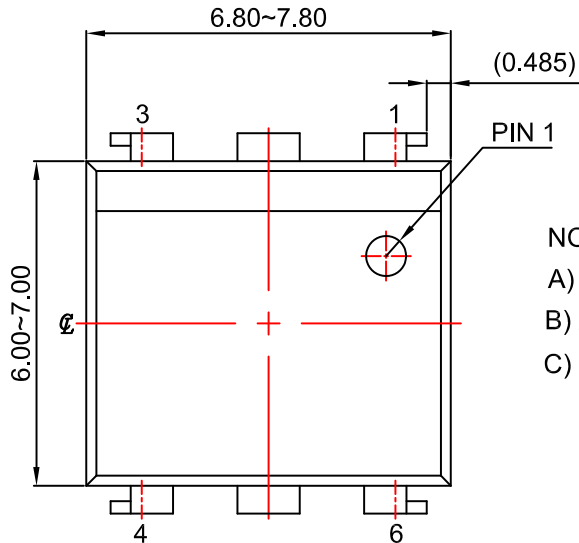
MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

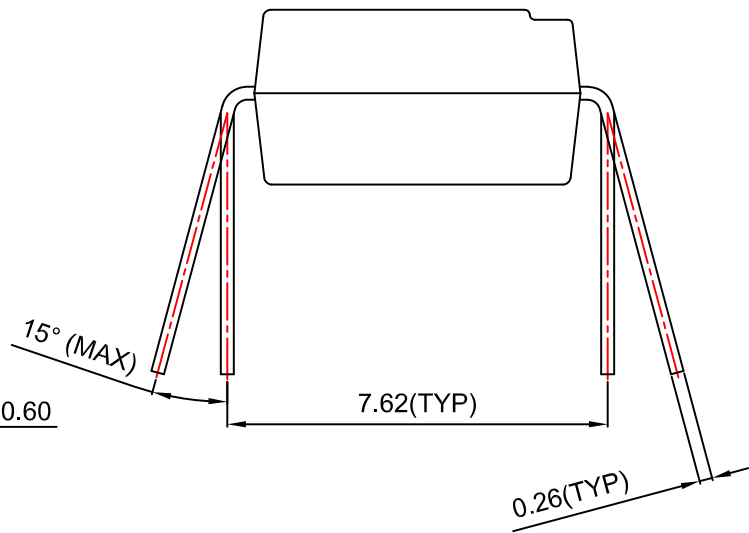
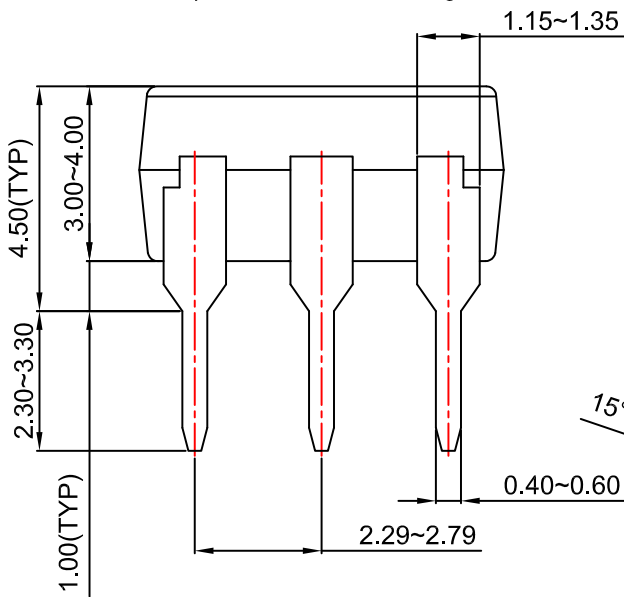


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CASE 709AG
ISSUE A

DATE 31 JUL 2016



- NOTES:
- A) NO STANDARD APPLIES TO THIS PACKAGE.
 - B) ALL DIMENSIONS ARE IN MILLIMETERS.
 - C) DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSION



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